

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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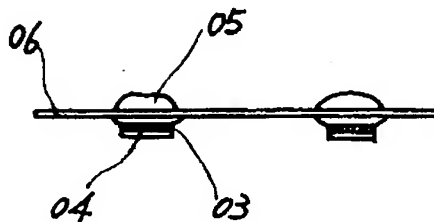
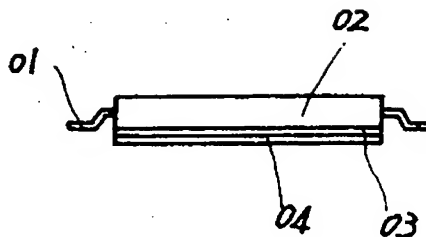
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APPLICANT : SEIKO EPSON CORP;

INVENTOR : KATO JUNICHI;

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TITLE : INTEGRATED CIRCUIT PACKAGE



ABSTRACT : PURPOSE: To facilitate the mounting work of an integrated circuit on a substrate by forming an adhesive bond or the like layer on the front or back surface of an integrated circuit package and covering the adhesive exposed surface with a protective film having adhesion preventing effect.

CONSTITUTION: An adhesive substance layer 03 made of thermoplastic adhesive or adhesive, e.g., acryl or the like and its protective film 04 are formed on one flat surface of a molded IC 02 of, for example, flat package type. In a film carrier type package, for example, an adhesive layer 03 and a protective film 04 are similarly formed on the surface contacted with the mounting substrate of an IC 05 formed on a flexible tape 06. In mounting on the substrate, the film 04 is removed, the ICs 02, 05 are bonded to the substrate, and lead terminal is soldered thereto. In this manner, it can simplify the mounting work inexpensively and can prevent the displacement of the mounting position.

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